

Polishing composition

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Abstract of **TW555840B**

A polishing composition comprising the following components (a) to (g): (a) at least one abrasive selected from the group consisting of silicon dioxide, aluminum oxide, cerium oxide, zirconium oxide and titanium oxide, (b) an aliphatic carboxylic acid, (c) at least one basic compound selected from the group consisting of an ammonium salt, an alkali metal salt, an alkaline earth metal salt, an organic amine compound and a quaternary ammonium salt, (d) at least one polishing accelerating compound selected from the group consisting of citric acid, oxalic acid, tartaric acid, glycine, alpha-alanine and histidine, (e) at least one anticorrosive selected from the group consisting of benzotriazole, benzimidazole, triazole, imidazole and tolyltriazole, (f) hydrogen peroxide, and (g) water.

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Asano et al.

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(45) **Date of Patent:** Jan. 20, 2004

(54) **POLISHING COMPOSITION AND
POLISHING METHOD EMPLOYING IT**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.** 51/308; 51/307; 51/309;
106/3; 438/692; 438/693

(58) **Field of Search** 51/307, 308, 309;
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(57) **ABSTRACT**

A polishing composition comprising the following components (a) to (g):

- (a) at least one abrasive selected from the group consisting of silicon dioxide, aluminum oxide, cerium oxide, zirconium oxide and titanium oxide,
- (b) an aliphatic carboxylic acid,
- (c) at least one basic compound selected from the group consisting of an ammonium salt, an alkali metal salt, an alkaline earth metal salt, an organic amine compound and a quaternary ammonium salt,
- (d) at least one polishing accelerating compound selected from the group consisting of citric acid, oxalic acid, tartaric acid, glycine, α -alanine and histidine,
- (e) at least one anticorrosive selected from the group consisting of benzotriazole, benzimidazole, triazole, imidazole and tolyltriazole,
- (f) hydrogen peroxide, and
- (g) water.

13 Claims, No Drawings